

Thermal connecting of lacquer-insulated wires

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Abstract of DE19829761

The method includes inserting and pressing the wires (4) on both sides or unilaterally in parallel in a conductor connector (1), and heating a solder block (3) in the interior of the connector. The maximum melting temperature of the solder lies underneath a softening temperature of the insulating lacquer. The wires are further inserted when the solder melts, until the open ends of the wires touch each other or the floor of the connector. The pressure is released, and a fixation of the wires and the connector is maintained until the solder has hardened. An Independent claim is provided for a corresponding conductor connector.

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